



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Eliezer Pasternak

Serial No.: 10/081,565

Group Art Unit: 2827

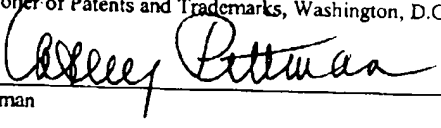
Filed: February 22, 2002

Examiner: Ishwarbhai B. Patel

Title: HIGH FREQUENCY DEVICE PACKAGES AND METHODS

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I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as FIRST CLASS MAIL in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on: March 4, 2003


Cathy Pittman

RESPONSE TO OFFICE ACTION

Commissioner for Patents and Trademarks
Washington, DC 20231

Dear Sir/Madam:

In response to the December 4, 2002 Office Action, Applicant requests that the Examiner consider the following remarks and amendments.

IN THE SPECIFICATION

In accordance with 37 C.F.R. 1.121(B)(1), Attachment A contains the marked up version indicating all the changes made.

Please replace the paragraph starting at page 4, line 17 with the following paragraph:

The invention is particularly applicable to microwave device packaging and it is in this context that the invention will be described. It will be appreciated, however, that the high frequency device package and packing method in accordance with the invention has greater utility since it can be used to package any device that operates at high frequencies or any device in which matched impedance vias and bonding wires are desirable.

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